

U.S. Patent Application Serial No. **09/889,577**  
Amendment dated February 23, 2004  
Attorney Docket No. 010610

**Amendments to the Abstract**

Please replace the Abstract with the following paragraph:

**ABSTRACT**

This is a cooler for dissipating heat away from an electronic device (A). The cooler includes a liquid cooling mechanism (B), a forcible air cooling mechanism (C) and a substrate (D). The liquid cooling mechanism includes a set of metal pipes (20-21) connected to a pump (3) with an impeller (16) to transfer cooling liquid to a liquid channel (4). The forcible air cooling mechanism (C) includes a fan (25) discharging air onto a radiating fin (37) located on the set of metal pipes (20-21). The substrates (D) is in fluid communication with the forcible air cooling mechanism (C) and the liquid cooling mechanism (B) and in direct contact with the electronic device (A) so as to remove heat away from the electronic device (A).